



NOTES:

- 1.) Rnwa and resistor designators 10+ for test purposes only
- 2.) xfmr: outer wdgs are 7/8/9, inner wdgs are 3/2/1; so two layers three wdgs each, #1 closest to center, #7 at legs ; embedded +/-6V7 secondaries between two primaries (sandwich)

Revision History	
Revision	Notes
A	* preliminary *
B	adjusted loop

Designed for: Public Release | Mod. Date: 7/10/2014  
 Project Title: Multi Output SEPIC for LCD display  
 Sheet Title:  
 Assembly Variant: Variant name not interpreted | Sheet: 1 of 1  
 File: PMP10051RevB.SchDoc | Size: A4  
 Drawn By:  
 Engineer: B.Geck | Contact: <http://www.ti.com/support>



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